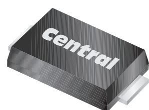
Material Composition Specification

SMAFL Case



Device average mass . . . . 32.5 mg

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.37%	0.77	Si	7440-21-3	2.37%	0.77	23,692
leadframe	copper alloy	53.4%	17.355	Cu	7440-50-8	53.32%	17.33	533,231
				Fe	7439-89-6	0.08%	0.025	769
die attach	high temperature solder paste	6.46%	2.1	Pb	7439-92-1	6.0%	1.95	60,000
				Sn	7440-31-5	0.29%	0.095	2,923
				Ag	7440-22-4	0.17%	0.055	1,692
encapsulation*	EMC GREEN	36.52%	11.87	silica (fused)	60676-86-0	28.15%	9.15	281,538
				epoxy resin	29690-82-2	3.63%	1.18	36,308
				phenol resin	9003-35-4	3.54%	1.15	35,385
				carbon black	1333-86-4	0.11%	0.035	1,077
				metal hydroxide	1309-42-8	1.09%	0.355	10,923
plating	matte tin	1.25%	0.405	Sn	7440-31-5	1.25%	0.405	12,462

*EMC GREEN molding compound is Halogen-Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.